

# SOT1092-3

plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.85 mm body

19 April 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN36
<b>Package type industry code</b>	HVQFN36
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-1-2012
<b>Manufacturer package code</b>	SOT1092

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.85	1	mm
A <sub>2</sub>	package height	-	-	-	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	

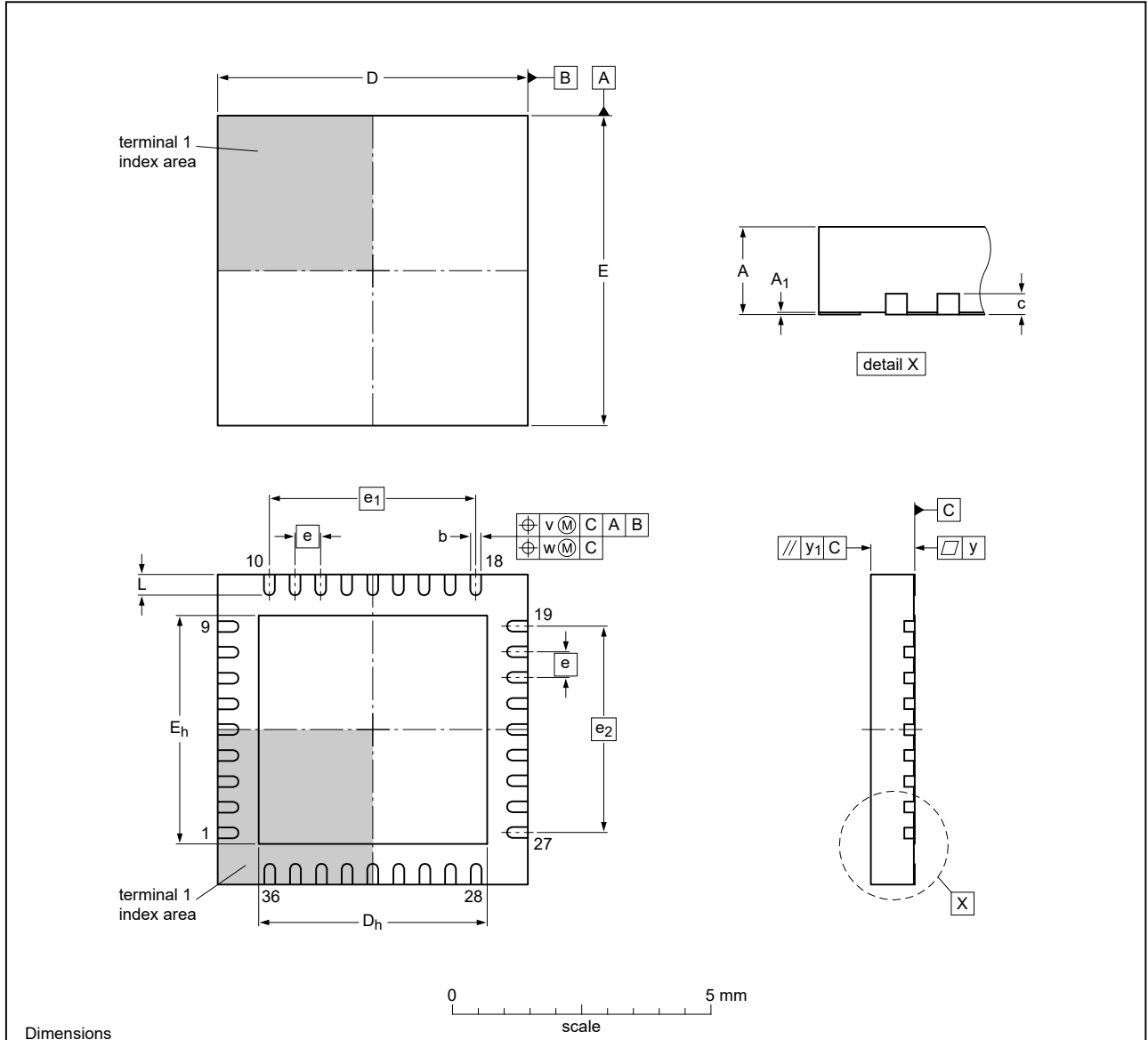


plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.85 mm x 0.85 mm body

## 2. Package outline

HVQFN36: plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; body 6 x 6 x 0.85 mm

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Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
max	1.00	0.05	0.30		6.1	4.55	6.1	4.55				0.50				
mm nom	0.85	0.02	0.21	0.2	6.0	4.40	6.0	4.40	0.5	4	4	0.40	0.1	0.05	0.05	0.1
min	0.80	0.00	0.18		5.9	4.25	5.9	4.25				0.30				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1092-2\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1092-3		MO-220	---		-11-12-14- 11-12-30

Fig. 1. Package outline HVQFN36 (SOT1092-3)

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### 3. Legal information

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